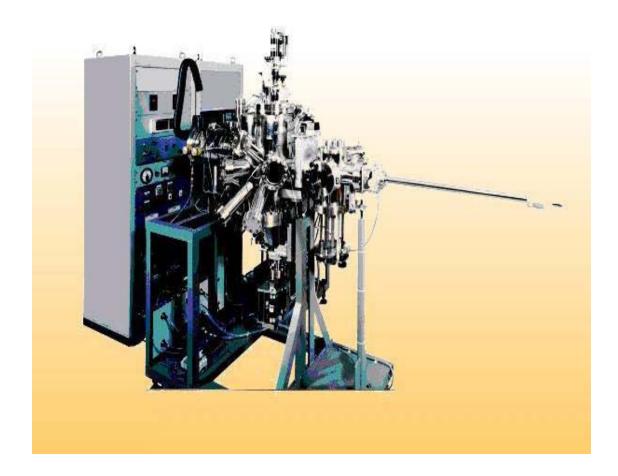
Compact Laser MBE system

Model: PA-C-PLMBE
Our design priority, easy-to-use, brings better controllability of film growth condition



<Outline>

This system is designed to deposit thin films on a substrate by the laser abrasion of target materials in an ultrahigh vacuum(UHV).

The apparatus consists of a deposition chamber, an infra-red heating lamp, a target revolution mechanism, and a RHEED chamber.

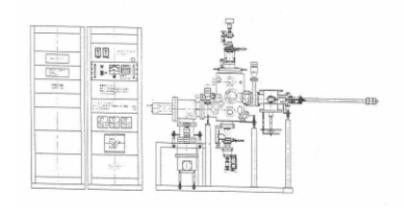
All of them are UHV compatible.

An Infra-red lamp heating that featured our apparatus can bring a substrate temperature more than 800°C and afford to deposit even in a high oxygen partial

pressure of higher than 500 mTorr.

Standard equipped load-lock transfar mechanism enable to keep deposition environment clean and bring easy-to-use.





<Feature>

- 1. Compact design that bring s an easy operation
- 2. Infra-red lanp heating
- 3. Magnetic coupled target rotation that enables the endless rotation
- 4. Easy operation of sunstrate (or target)exchange by transfer rod
 - 5. Auxiliary ports for mounting various components

$\langle Specification \rangle$

1.Growth chamber	Arrival pressure	\leq 6.7 × 10 ⁻⁷ Pa(5 × 10 ⁻⁹ Torr)
	Chamber	ca.300mm diam. × 500mm high. cylindrical(SUS304)
	Exhaust speed	≦10 ⁻⁴ Pa(10 ⁻⁶ Torr)in 20 minutes
		Heating temperature :≧800°Cwithin 15−mm square of substrate holder
		Temperature uniformity :smaller than ±2.5°Cwithin 15-mm square
	Substrate holder with radiation heating by infrared lamp	Substrate size: MAX 50mm diam. Substrate movement: Horizontal X: ±10mm Y: ±10mm Vertical: Z1: ±20mm Sample exchange: Z2: ±0~20mm Rotation: AC motor driven Shutter for substrate CF1.33",pneumatic Flange CF10" Water cooling Power control: Programmable PID controlled DC power supply
	Target holder with revolver	Thermocouple: Type R Target loading 20mm diam. × 4(6 個: optional) Target movement Horizontal X:±10mm Y:±10mm Vertical Z:±20mm Target spin mechanism: Motor driven via mgnetic rotation feedthrough
		Revolution mechanism: Stepping-motor driven

	Process gas flow	via variable leak valve for O_2 via manual valve for O_2 at around atmospheric pressure
		reserve port for gas inlet
	Laser irradiation	via synthesized quartz window(CF4.5")at an angle of 45° to a target
		Window trasparency ≧93% for ArF ≧93% for KrF
	Vacuum	for UHV : nude ionization gauge for low vacuum : Capacitance manometor 1Torr
	Pumps	Main pump : magnetic-bearing TMP(800L/s)for wide-vacuum-range use
		Rotary pump: 275L/m Main valve: 6"pneumatic Baypass line: pneumatic and manual operation Pressure monitor
	Bake-out heater	Sheath heater and tape heater Temperature controllable range: 100°C~ 200°C
	Ports	for target observation CF6" for thickness monitor or mask CF6" for cells CF4.5" × 2 for temperature measurement CF4.5" for gasintroduction CF2.75" for RHEED(gun and screen) CF4.5" for gun/CF6" for screen
2. Load-lock and substrate transfer mechanism	Load-lock chamber: ca.150mm diam. × 200mm high.(SUS304) Ultimate pressure: 6.7 × 10 ⁻⁵ Pa (5 × 10 ⁻⁷ Torr) Access door with window Sample capacity: 2 substrates and 4 targets Vent line	

	auxiliary port : CF2.75"		
	Pumps : 70L/s TMP and Rotary pump		
	Vacuum gauge		
	Substrate transfer : Magnetic coupled transfer rod X-Y		
	movable stage		
	Gate valve to the growth chamber : 4"manual valve		
	Bake-out heater : Tape heater 2m × 5		
3.system rack	JIS standard rack for controllers and power supplies ×2		
	AC100V 1 Ø 50A		
	AC200V 3 ϕ 50A		
	Dry N_2 gas		
4.Utilities	compressed air 5kg/cm ² (pressure regulator supplies)		
	Cooling water		
	Any construction of laboratory room is not included.		
	Gases for user's process are not included.		
	Electro-manually controlled power supply : control of		
	vaccum valve		
	Interlock : Deficient flow of cooling water for infrared lamp		
	heating		
5.Control system	Deficient pressure of compressed air for		
	pneumatic valve drive		
	Preservation of high vacuum in each chamber		
	after an electric power failure(Manual recovery only)		
	Urgent shutdown function		

<Option>

Differentially pumped RHEED gun
2-stage differentially pumped RHEED gun
Scanning RHEED gun
RHEED pattern processing system
Laser diode heating component /6 targets
Target-laser synchronizer (PC and software)
Encounter mask mechanisms
Radigcal beam source
Ozone source(or ozonizer component)

Pyrometer

Laser for abration ; Nd:YAG(3ω 355nm) Laser for abration ; Excimer(KrF 248nm) Optics components and optical box

• Specifications may subject to change for improvement without notice.

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